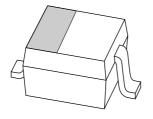
DISCRETE SEMICONDUCTORS

DATA SHEET

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BAP1321-03 Silicon PIN diode

Product specification
Supersedes data of 2001 May 11

2004 Feb 17





Silicon PIN diode BAP1321-03

FEATURES

- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Very low series inductance
- For applications up to 3 GHz.

APPLICATIONS

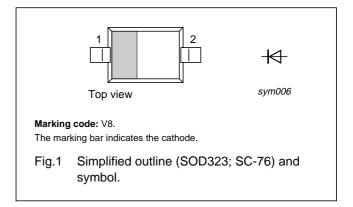
• RF attenuators and switches.

DESCRIPTION

Planar PIN diode in a SOD323 (SC-76) ultra small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



ORDERING INFORMATION

TYPE	PACKAGE				
NUMBER	NAME	DESCRIPTION	VERSION		
BAP1321-03	_	plastic surface mounted package; 2 leads	SOD323		

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		_	60	V
I _F	continuous forward current		_	100	mA
P _{tot}	total power dissipation	T _s ≤ 90 °C	_	500	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

Silicon PIN diode

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CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	TYP.	MAX.	UNIT	
V _F	forward voltage	I _F = 50 mA	0.95	1.1	V
I _R	reverse leakage current	V _R = 60 V	_	100	nA
C _d	diode capacitance	V _R = 0; f = 1 MHz	0.4	_	pF
et4U.com		V _R = 1 V; f = 1 MHz	0.35	0.45	pF
		V _R = 20 V; f = 1 MHz	0.25	0.32	pF
r _D	diode forward resistance	f = 100 MHz; note 1			
		$I_F = 0.5 \text{ mA}$	3.4	5.0	Ω
		I _F = 1 mA	2.4	3.6	Ω
		I _F = 10 mA	1.2	1.8	Ω
		I _F = 100 mA	0.85	1.3	Ω
S ₂₁ ²	isolation	V _R = 0; f = 900 MHz	16.6	_	dB
		V _R = 0; f = 1800 MHz	11.6	_	dB
		V _R = 0; f = 2450 MHz	9.2	_	dB
S ₂₁ ²	insertion loss	I _F = 0.5 mA; f = 900 MHz	0.26	_	dB
		I _F = 0.5 mA; f = 1800 MHz	0.35	_	dB
		I _F = 0.5 mA; f = 2450 MHz	0.44	_	dB
S ₂₁ ²	insertion loss	I _F = 1 mA; f = 900 MHz	0.20	_	dB
		I _F = 1 mA; f = 1800 MHz	0.29	_	dB
		I _F = 1 mA; f = 2450 MHz	0.38	_	dB
S ₂₁ ²	insertion loss	I _F = 10 mA; f = 900 MHz	0.13	_	dB
		I _F = 10 mA; f = 1800 MHz	0.22	_	dB
		I _F = 10 mA; f = 2450 MHz	0.32	_	dB
S ₂₁ ²	insertion loss	I _F = 100 mA; f = 900 MHz	0.10	_	dB
		I _F = 100 mA; f = 1800 MHz	0.20	_	dB
		I _F = 100 mA; f = 2450 MHz	0.29	_	dB
τ∟	charge carrier life time	when switched from I_F = 10 mA to I_R = 6 mA; R_L = 100 Ω ; measured at I_R = 3 mA	0.5	-	μѕ
L _S	series inductance	I _F = 100 mA; f = 100 MHz	1.5	_	nH

Note

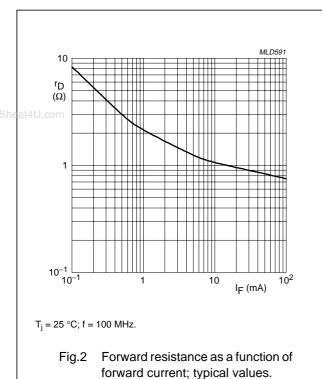
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th(j-s)}	thermal resistance from junction to soldering point	120	K/W

^{1.} Guaranteed on AQL basis: inspection level S4, AQL 1.0.

Silicon PIN diode BAP1321-03

GRAPHICAL DATA



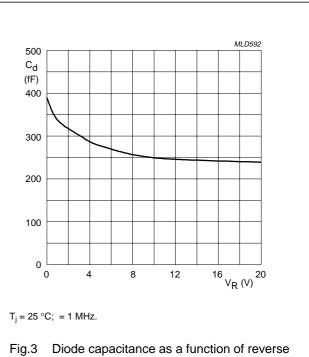
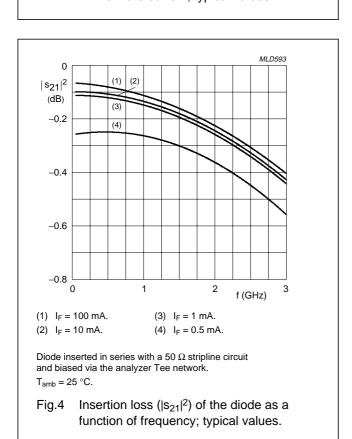
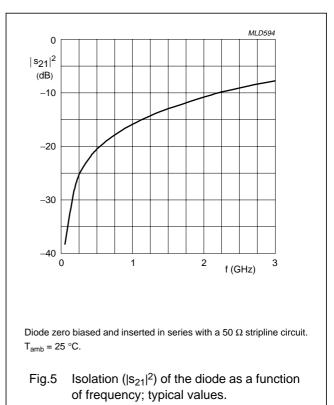


Fig.3 Diode capacitance as a function of reverse voltage; typical values.





Silicon PIN diode

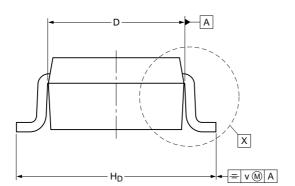
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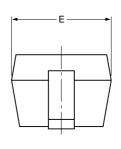
PACKAGE OUTLINE

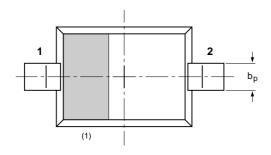
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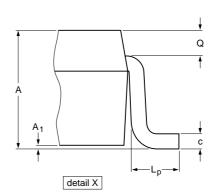
Plastic surface mounted package; 2 leads

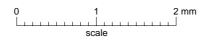
SOD323











DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	bp	С	D	E	H _D	Lp	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOD323			SC-76			99-09-13 03-12-17	

Silicon PIN diode

BAP1321-03

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
el4U.com	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

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